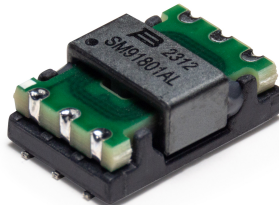


MATERIAL DECLARATION SHEET

BOURNS®

Material Number	SM91801AL Family			
Product Line	Signal Transformer			
Compliance Date	2024-02-20			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\Substances	CASRN(if applicable)	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Core	Mn-Zn ferrite	0.4645	Ferric oxide	1309-37-1	70	28.4496	40.6422
				Trimanganese tetraoxide	1317-35-7	22	8.9413	
				Zinc oxide	1314-13-2	8	3.2514	
2	PCB board	Cu-ETP	0.102	Copper	7440-50-8	99.95	8.9202	8.9247
				Miscellaneous	Not to declare	0.05	0.0045	
		Glass fiber	0.071	Silicon dioxide	60676-86-0	53.69	3.3354	6.2123
				Calcium oxide	1305-78-8	22.11	1.3735	
				Aluminum oxide	1344-28-1	13.68	0.8498	
				Magnesium oxide	1309-48-4	3.26	0.2025	
				Miscellaneous	Not to declare	7.26	0.4510	
		Epoxy resin	0.086	Epoxy resin	Proprietary	92.5	6.9604	7.5247
				Miscellaneous	Not to declare	7.5	0.5644	
		EPA-EP-resin (Green)	0.01	Copolymer of modified epoxy acrylate resin and epoxy resin	Proprietary	58.38	0.5108	0.8750
				Barium sulphate	7727-43-7	28.31	0.2477	
				Silica gel	112926-00-8	6.99	0.0612	

MATERIAL DECLARATION SHEET

BOURNS®

				Further additives	Not to declare	1.99	0.0174	0.0875
				Miscellaneous	Not to declare	4.33	0.0379	
		Epoxy resin(White Marking Ink)	0.001	Epoxy resin	Proprietary	38.7	0.0339	
				Barium sulfate	7727-43-7	15.8	0.0138	
				Talc	14807-96-6	9.9	0.0087	
				Titanium dioxide	13463-67-7	33.7	0.0295	
				Inorganic Ingredient	Not to declare	1.4	0.0012	
				Further additives	Not to declare	0.5	0.0004	
3	Base	Diallyl phthalate molding compound	0.3417	DAP resin	25035-78-3	25	7.4744	29.8976
				Aluminum trihydroxide	21645-51-2	45	13.4539	
				Glass fiber	65997-17-3	30	8.9693	
4	Terminal pin	Phosphor bronze alloys	0.028	Copper	7440-50-8	93.45	2.2894	2.4499
				Tin	7440-31-5	6.25	0.1531	
				Phosphorus	7723-14-0	0.2	0.0049	
				Iron	7439-89-6	0.1	0.0024	
		Tin plating	0.0015	Tin	7440-31-5	100	0.1312	0.1312
		Nickel plating	0.0005	Nickel	7440-02-0	100	0.0437	0.0437
5	Glue	Acrylates copolymer	0.00072	Acrylates copolymer	25133-97-5	100	0.0630	0.0630
6	Glue	Epoxy resin	0.00338	Epoxy resin	38891-59-7	95	0.2810	0.2957
				Bentonite	1302-78-9	5	0.0148	
7	Solder	Tin-copper alloy	0.0326	Tin	7440-31-5	99.3	2.8324	2.8524
				Copper	7440-50-8	0.7	0.0200	
		Total weight	1.14					

This Document was updated on: 2024-02-20

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.